

MA200WK

Silicon epitaxial planer type

For switching circuits

■ Features

- Small reverse current I_R , with extremely small leakage current
- t_{rr} of a soft recovery type

■ Absolute Maximum Ratings ($T_a=25^\circ\text{C}$)

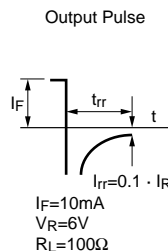
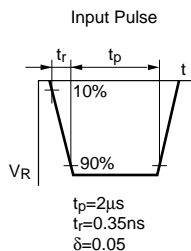
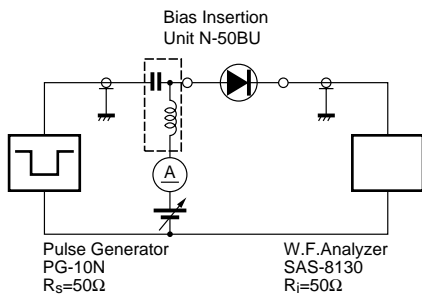
Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	80	V
Peak reverse voltage	V_{RM}	80	V
Forward current (DC)	Single	100	mA
	Double	150	
Peak forward current	Single	225	mA
	Double	340	
Non-repetitive peak forward surge current	Single	500	mA
	Double	750	
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	- 55 to +150	$^\circ\text{C}$

* $t=1s$

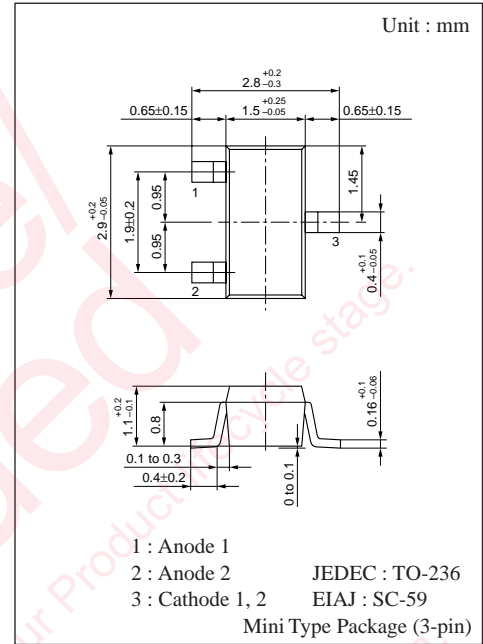
■ Electrical Characteristics ($T_a=25^\circ\text{C}$)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	I_{R1}	$V_R=75V$			100	nA
	I_{R2}	$V_R=5V, T_a=85^\circ\text{C}$			20	nA
Forward voltage (DC)	V_F	$I_F=100mA$			1.2	V
Reverse voltage (DC)	V_R	$I_R=100\mu A$	80			V
Terminal capacitance	C_t	$V_R=0V, f=1MHz$			2.5	pF
Reverse recovery time	t_{rr} *	$I_F=10mA, V_R=6V$ $I_{rr}=0.1 \cdot I_R, R_L=100\Omega$			100	ns

Note 1 : Rated input/output frequency : 100MHz
2 : * t_{rr} measuring circuit

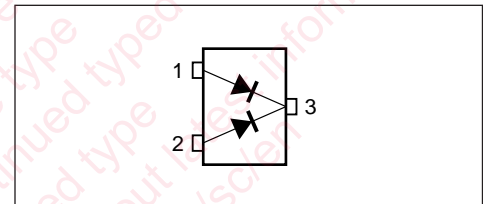


■ Marking

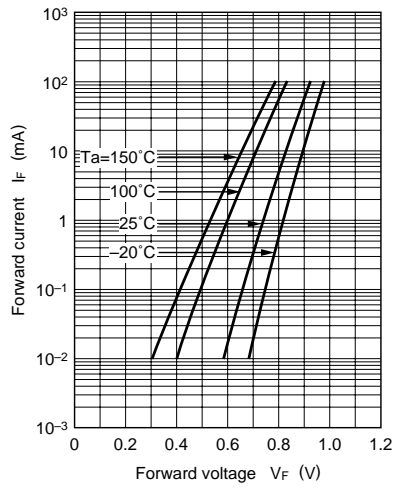


Marking Symbol : M4D

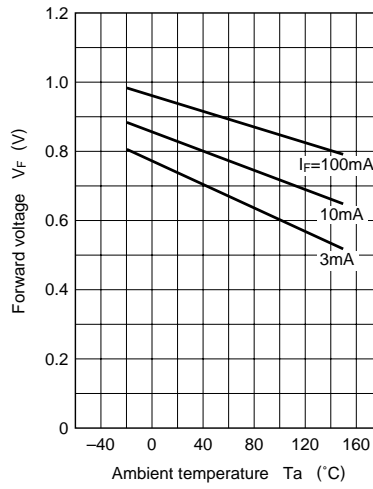
■ Internal Connection



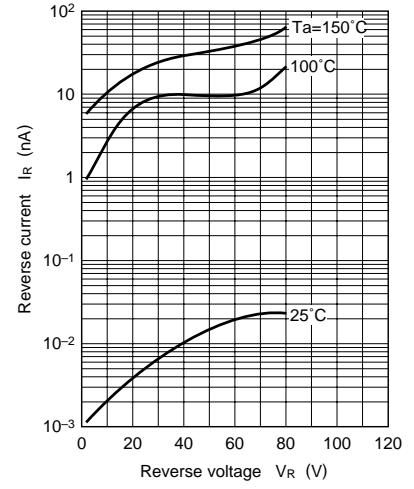
$I_F - V_F$



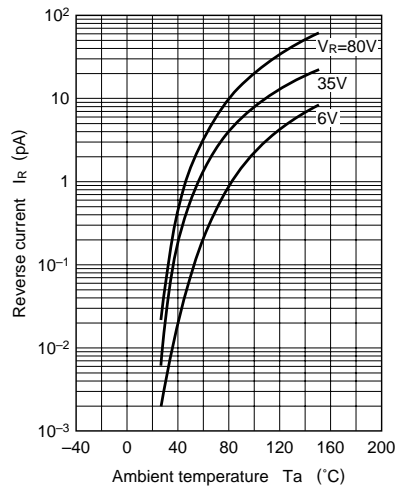
$V_F - T_a$



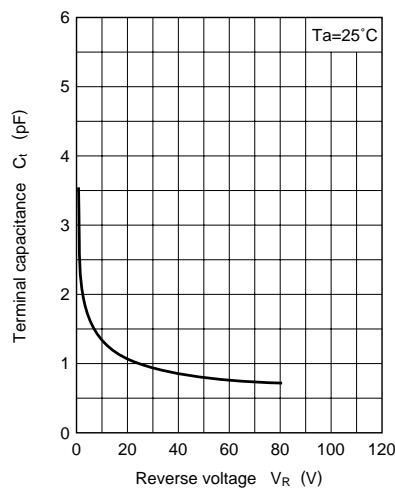
$I_R - V_R$



$I_R - T_a$



$C_t - V_R$



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